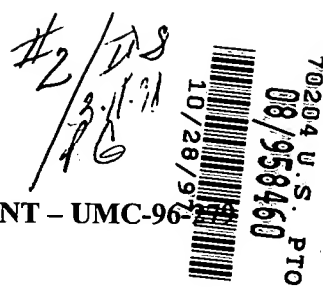


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PATENT - UMC-96-24



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:	)	
Chih-Chien Liu, et al.	)	Art Unit: Not Assigned
Serial No.: Not Assigned	)	
Filed: Herewith	)	Examiner: Not Assigned
For: High Density Plasma Chemical Vapor Deposition	)	
Process	)	

Information Disclosure Statement

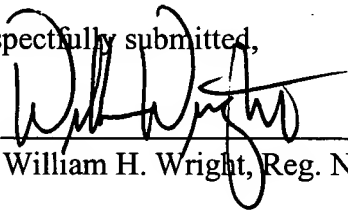
Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Enclosed is a Form PTO-1449, Information Disclosure Citation in an Application. The following documents are submitted herewith to comply with the duty of disclosure under CFR 1.97-1.98 and 37 CFR 1.56:

1. The article by J.T. Pye, et al., "*High-Density Plasma CVD and CMP for 0.25- $\mu$ m Intermetal Dielectric Processing*," Solid State Technology, December 1995, pp.65-69.

Respectfully submitted,

By:   
William H. Wright, Reg. No. 36, 312

Dated: October 28, 1997

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